The product described herein has not been fully tested to ensure conformance to the requirements outlined below. TE Connectivity makes no representation or warranty, express or implied, that the product will comply with these requirements. Further, TE may change these requirements based on the results of additional testing and evaluation. Contact TE Engineering for further details.

Design Objective (108-115188)

1.5mm Pitch Double Row WTB with Latch

- 1. Scope:
- 1.1 Contents:

This specification covers the requirements for product performance, test methods and quality assurance provisions of 1.5mm Pitch Double Row Wire to Board Connector with Latch Applicable product description and part numbers are as shown in Fig.1.

2. Applicable Documents

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements this specification and referenced documents, this specification shall take precedence.

- 2.1 AMP Specifications:
 - A. 109-5000 Test Specification, General Requirements for Test Methods
 - B. 501-115203 Test Report
- 2.2 Commercial Standards and Specifications:
 - A. EIA-364: Test Methods for Electronic and Electrical Component Parts.

(Always use latest version for test)

The application product descriptions and part numbers are as shown in Fig. 1

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| Т | | | | 20 | 1 of 16 | 1.5mm | Pitch D/R Wire to Board (| Connecto | r |
| | LTR | REVISION RECORD | DR | DATE | | | | | |

| Product Part No. | Description |
|------------------|---|
| 2394528-1 | Cable Housing of 1.5mm Pitch 10Pos WTB with Latch |
| 2394528-2 | Cable Housing of 1.5mm Pitch 20Pos WTB with Latch |
| 2394528-3 | Cable Housing of 1.5mm Pitch 30Pos WTB with Latch |
| 2380403-1 | ST type Tin PL Cable Contact of 1.5mm Pitch WTB with Latch |
| 2380403-2 | ST type Au Flash Cable Contact of 1.5mm Pitch WTB with Latch |
| 2380403-3 | HP type Tin PL Cable Contact of 1.5mm Pitch WTB with Latch |
| 2380403-4 | HP type Au Flash Cable Contact of 1.5mm Pitch WTB with Latch |
| 2394521-1 | R/A HP Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 2394521-2 | R/A HP Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 2394521-3 | R/A HP Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 1-2394521-1 | R/A HP Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 1-2394521-2 | R/A HP Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 1-2394521-3 | R/A HP Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 2-2394521-1 | R/A HP Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 2-2394521-2 | R/A HP Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 2-2394521-3 | R/A HP Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |
| 3-2394521-1 | R/A HP Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 3-2394521-2 | R/A HP Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 3-2394521-3 | R/A HP Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |
| 4-2394521-1 | R/A ST Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 4-2394521-2 | R/A ST Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 4-2394521-3 | R/A ST Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 5-2394521-1 | R/A ST Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 5-2394521-2 | R/A ST Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 5-2394521-3 | R/A ST Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 6-2394521-1 | R/A ST Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 6-2394521-2 | R/A ST Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 6-2394521-3 | R/A ST Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |
| 7-2394521-1 | R/A ST Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 7-2394521-2 | R/A ST Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 7-2394521-3 | R/A ST Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |

Fig. 1 (to be continue)

| | • | | | | |
|--------------|-----------------|------|------------|-----|-----|
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| Product Part No. | Description |
|------------------|--|
| 2394520-1 | Vertical HP Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 2394520-2 | Vertical HP Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 2394520-3 | Vertical HP Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 1-2394520-1 | Vertical HP Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 1-2394520-2 | Vertical HP Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 1-2394520-3 | Vertical HP Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 2-2394520-1 | Vertical HP Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 2-2394520-2 | Vertical HP Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 2-2394520-3 | Vertical HP Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |
| 3-2394520-1 | Vertical HP Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 3-2394520-2 | Vertical HP Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 3-2394520-3 | Vertical HP Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |
| 4-2394520-1 | Vertical ST Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 4-2394520-2 | Vertical ST Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 4-2394520-3 | Vertical ST Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 5-2394520-1 | Vertical ST Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Natural |
| 5-2394520-2 | Vertical ST Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Natural |
| 5-2394520-3 | Vertical ST Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Natural |
| 6-2394520-1 | Vertical ST Type Au Flash Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 6-2394520-2 | Vertical ST Type Au Flash Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 6-2394520-3 | Vertical ST Type Au Flash Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |
| 7-2394520-1 | Vertical ST Type Tin PL Board Side of 1.5mm Pitch 10Pos WTB with Latch Black |
| 7-2394520-2 | Vertical ST Type Tin PL Board Side of 1.5mm Pitch 20Pos WTB with Latch Black |
| 7-2394520-3 | Vertical ST Type Tin PL Board Side of 1.5mm Pitch 30Pos WTB with Latch Black |

Fig. 1 (End)

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| connectivity | | 3 | 108-115188 | A | ES |

- 3. Requirements:
- 3.1 Design and Construction:

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

- 3.2 Materials:
 - A. Board side:

Contacts: Gold plating or Tin plating, Copper Alloy

Housing: LCP, UL94V-0, Natural or Black

Metal Peg: Tin plating, Copper Alloy

B. Cable side:

Contacts: Gold plating or Tin plating, Copper Alloy

Housing: Nylon, UL94V-0, Natural or Black

- 3.3 Ratings:
 - A. Voltage Rating: 50 Volts AC (per pin)
 - B. Current Rating (Maximum)

AWG # 24: 3.0 A (per pin) *1

AWG # 24: 2.0 A (per pin) *2

AWG # 26: 2.0 A (per pin)

AWG # 28: 1.5 A (per pin)

AWG # 30: 1.0 A (per pin)

*1: For HP Type

*2: For ST Type

C. Temperature Rating: -40°C to +105°C

The upper limit of the temperature includes the temperature rising resulted by the energized electrical current.

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| connectivity | | 4 | 108-115188 | Α | ES |

3.4 Performance Requirements and Test Descriptions:

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig.2. All tests shall be performed in the room temperature unless otherwise specified.

3.5 Test Requirements and Procedures Summary:

| Para. | Test Items | Requirements | Procedures |
|---------|---------------------------------------|--|--|
| 3.6.1 | Examination of product | Product shall be confirming to the requirements of applicable product drawing and applicable Specification | Visual and Dimensional Inspection Test Procedure for Electrical Connectors. EIA-364-18 |
| Electri | ical Requirements | | |
| 3.6.2 | Termination Resistance (Low Level) | 20 mΩ Max. (Initial) ΔR <10 mΩ (Final) | Subject mated contacts assembled in housing to 20mV Max. open circuit at 10 mA. EIA-364-23 |
| 3.6.3 | Dielectric withstanding voltage | No creeping discharge or flashover shall occur. Current leakage: 1mA Max. | 500 VAC Min. at sea level for 1 minute Test between adjacent contacts of unmated connectors. (EIA-364-20) |
| 3.6.4 | Insulation Resistance | 1000 MΩ Min | Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21) |
| 3.6.5 | Temperature Rising | 30°C max, when apply current rate | Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70 METHOD 2) |

Fig.2. To be continued

| =TE | TE Connectivity | PAGE | NO | REV | LOC |
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| connectivity | | 5 | 108-115188 | A | ES |

| Para. | Test items | | Requirements | | | Procedures | | |
|-----------------|---------------------------------|----------|---------------|--------|----|---|--|----|
| Mechani | ical Requireme | nts | | | | | | |
| 3.6.6 Connector | | | See Table 5 | | | Operation Speed: | | |
| | Mating/Unm Force | ating | | | | 25.4 ± 3 mm/minute | | |
| | | | | | | Measure the force required to macconnector. | ate/unmat | ed |
| | | | | | | Unmated connector angle θ is +/max. See figure 1 | -20 degre | e |
| | | | | | | (EIA-364-13) | | |
| 3.6.7 | Durability (F Mate/Unmat | | 30 cycles | | | The sample should be mounted in and fully mated and unmated the cycles specified at the rate of | | |
| | | | | | | $25.4 \pm 3 \text{mm/min}.$ | | |
| | | | | | | (EIA-364-09) | counted in the tester ated the number of the | |
| 3.6.8 | Vibration (L Frequency) | ow | 1 us Max. | | | The electrical load condition sham M maximum for all contacts. So a simple harmonic motion havin amplitude of 0.76mm (1.52mm total excursion) in frequency bet limits of 10 and 55 Hz. The entifrequency range, from 10 to 55 Hz return to 10 Hz, shall be traverse approximately 1 minute. This m shall be applied for 2 hours in eathree mutually perpendicular directions. | Subject to g maximum ween the re Hz and ed in action ach of | |
| | | | | | | (EIA-364-28 Condition I) | | |
| 3.6.9 | Physical Sho | ock | 1 us Max. | | | Subject mated connectors to 50 G's (peak value) half-sine she of 11 milliseconds duration. The in each direction shall be applied three mutually perpendicular axe test specimen (18 shocks). The load condition shall be 100mA in for all contacts. (EIA-364-27, test condition A) | ree shocks I along the es of the electrical | 3 |
| 3.6.10 | Contact Rete | | 0.40 kgf Min. | | | Operation Speed: | | |
| | Force of Boa | ird side | | | | 25.4 ± 3 mm/minute. | | |
| | | | | | | Measure the contact retention fo Tensile strength tester. | rce with | |
| 3.6.11 | crimping | | 0.50 kgf Min. | | | Operation Speed: | | |
| | Terminal F | | | | | 25.4 ± 3 mm/minute. | | |
| | Strength of housing (Cable size | | | | | Measure the Terminal retention Tensile strength tester. | force with | l |
| | | <i>'</i> | | , | | | | _ |
| TE (| | | Connectivity | PAGE 6 | No | O 108-115188 | REV A | L |

| 3.6.12 | Wire Crimping | AWG# 24: 2.5Kgf Min | Pull wire axially from at the speed |
|--------|-----------------------|----------------------|-------------------------------------|
| | Strength | AWG# 26: 2.0Kgf Min | rate of 25.4 ± 3 mm/min. |
| | | AWG# 28: 1.0Kgf Min | |
| | | AWG# 30: 0.5Kgf Min. | |
| 3.6.13 | Board Lock Pull | 1.0kgf Min. | Operation Speed: |
| | Strength of Wire Lock | | 25.4 ± 3 mm/minute. |
| | LOCK | | Measure the Board Lock Pull |
| | | | Strength of Wire Lock. |

Fig. 2 (To be continued)

| TE | TE Connectivity | PAGE | NO | REV | LOC |
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| connectivity | | 7 | 108-115188 | A | ES |

| Para | Test Items | Requirements | Procedures |
|---------|----------------------------------|--|--|
| Enviror | nmental Requirements | | |
| 3.6.14 | Thermal Shock | See Product Qualification and Test Sequence Group 4 | Mate module and subject to follow condition for 5 cycles. |
| | | | 1 cycles: |
| | | | -40 +0/-3 °C, 30 minutes |
| | | | +85 +3/-0 °C, 30 minutes |
| | | | (EIA-364-32, test condition A) |
| 3.6.15 | Humidity | See Product Qualification and Test Sequence Group 4 | Mated Connector |
| | | 1 est sequence Group 4 | 40°C, 90~95% RH, |
| | | | 96 hours. |
| | | | (EIA-364-31,Condition A, Method II) |
| 3.6.16 | Salt Spray (Only for GOLD) | See Product Qualification and Test Sequence Group 12 | Subject mated/unmated connectors to 5% salt-solution concentration, 35°C for 24 hours. |
| | , | | (EIA-364-26,Test condition B) |
| 3.6.17 | Temperature Life (Heat Aging) | See Product Qualification and | Subject mated connectors to temperature life at 105°C for 96 hours. |
| | | Test Sequence Group 5 | (EIA-364-17, Test condition A) |
| 3.6.18 | Solderability | Solder able area shall have minimum of 95% solder coverage. | Subject the test area of contacts into the flux for 5-10 sec. And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. |
| | | | (EIA-364-52) |
| 3.6.19 | | | Pre Heat: 150°C~180°C, 60~120sec. |
| | Resistance to Reflow | See Product Qualification and Test Sequence Group 6 (Lead | Heat: 230°C Min., 40sec Min. |
| | Soldering Heat | Free) | Peak Temp.: 260°CMax, |
| | | | 10sec Max. |

Note. Flowing Mixed Gas shell be conduct by customer request.

Fig. 2 (End)

| = TF | TE Connectivity | PAGE | NO | REV | LOC |
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| connectivity | | 8 | 108-115188 | A | ES |

4. PRODUCT QUALIFICATION AND TEST SEQUENCE

| | | | | | Te | st Gr | oup | | | | | |
|--|---------------|-----|-----|------|-----|-------|-----|---|---|----|----|-----|
| Test or Examination | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 |
| | Test Sequence | | | | | | | | | | | |
| Examination of Product | | | | 1,7 | 1,6 | 1,4 | | | | | | 1,4 |
| Low Level Contact Resistance | | 1,5 | 1,4 | 2,10 | 2,9 | 2,5 | | | | | | 2,5 |
| Insulation Resistance | | | | 3,9 | 3,8 | | | | | | | |
| Dielectric Withstanding Voltage | | | | 4,8 | 4,7 | | | | | | | |
| Temperature rise | 1 | | | | | | | | | | | |
| Mating / Unmating Forces | | 2,4 | | | | | | | | | | |
| Durability | | 3 | | | | | | | | | | |
| Contact Retention Force (Board Side) | | | | | | | | 1 | | | | |
| Vibration | | | 2 | | | | | | | | | |
| Shock (Mechanical) | | | 3 | | | | | | | | | |
| Thermal Shock | | | | 5 | | | | | | | | |
| Humidity | | | | 6 | | | | | | | | |
| Temperature life | | | | | 5 | | | | | | | |
| Salt Spray | | | | | | | | | | | | 3 |
| Crimping Terminal Pull Strength of | | | | | | | | | 1 | | | |
| the housing (Cable size) | | | | | | | | | | | | |
| Board Lock Pull Strength of Wire Lock | | | | | | | | | | 1 | | |
| Wire Crimping Strength | | | | | | | | | | | 1 | |
| Solder ability | | | | | | | 1 | | | | | |
| Resistance to Soldering Heat | | | | | | 3 | | | | | | |

Numbers indicate sequence in which the tests are performed.

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| connectivity | | 9 | 108-115188 | A | ES |

5. Mating / Unmating Force:

Unit: N

| | At in | At 30th | | |
|----------|-----------------------|---------------------------|---------------------------|--|
| Pos. No. | Mating Force. (Max) | Unmating Force (Min) | Unmating Force (Min) | |
| 10 | 40 | 4 | 4 | |
| 20 | 70 | 7 | 7 | |
| 30 | 80 | 8 | 8 | |

Table 5

6. INFRARED REFLOW CONDITION

TEMPERATURE CONDITION GRAPH (TEMPERATURE ON BOARD PATTERN SIDE)

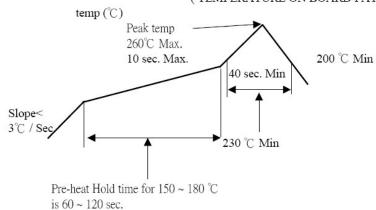
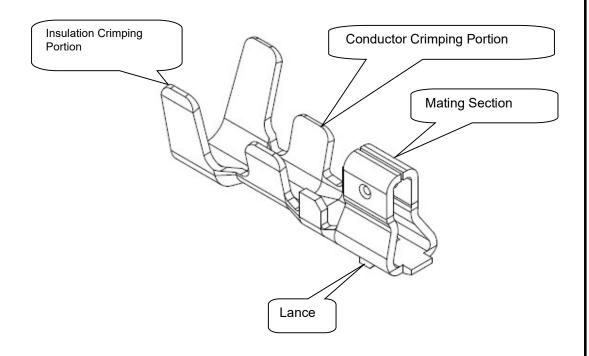


Fig. 6

| | | 1 | | | |
|--------------|-----------------|------|------------|-----|-----|
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| connectivity | | 10 | 108-115188 | A | ES |

7. ANATOMY OF CRIMPING TERMINAL



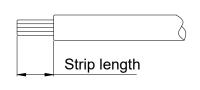
8. APPLICABLE WIRES: UL10584 ETFE WIRE

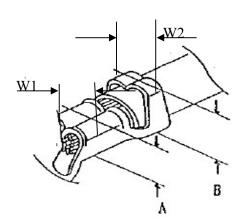
AWG Size:AWG#30~#24 Insulation OD: Φ0.70~1.00mm

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| connectivity | | 11 | 108-115188 | Α | ES |

9. CRIMPING CONDITION

| CRIMPING CONDITION | | | | | | | | | | |
|--------------------|----------|----------------|------------|-----------|------------|------------------|------------|--|--|--|
| Part Number | V | Vire Specifica | tion | Crimp He | ight (mm) | Crimp Width (mm) | | | | |
| | UL Style | AWG Size | Insulation | Conductor | Insulation | Conductor | Insulation | | | |
| | (REF.) | AWG Size | OD(mm) | A | В | W1 | W2 | | | |
| | UL1061 | 24 | 1.10 | 0.52~0.58 | 1.57~1.63 | 0.90(Ref) | 1.05 max. | | | |
| 2380403-* | UL1061 | 26 | 1.00 | 0.52~0.58 | 1.47~1.53 | 0.80(Ref.) | 1.05 max. | | | |
| 2300103 | UL1061 | 28 | 0.90 | 0.52~0.58 | 1.37~1.43 | 0.70(Ref.) | 1.05 max. | | | |
| | UL1061 | 30 | 0.70 | 0.52~0.58 | 1.25~1.31 | 0.60(Ref.) | 1.05 max. | | | |





Note:

1 · W1: Conductor Crimping Width

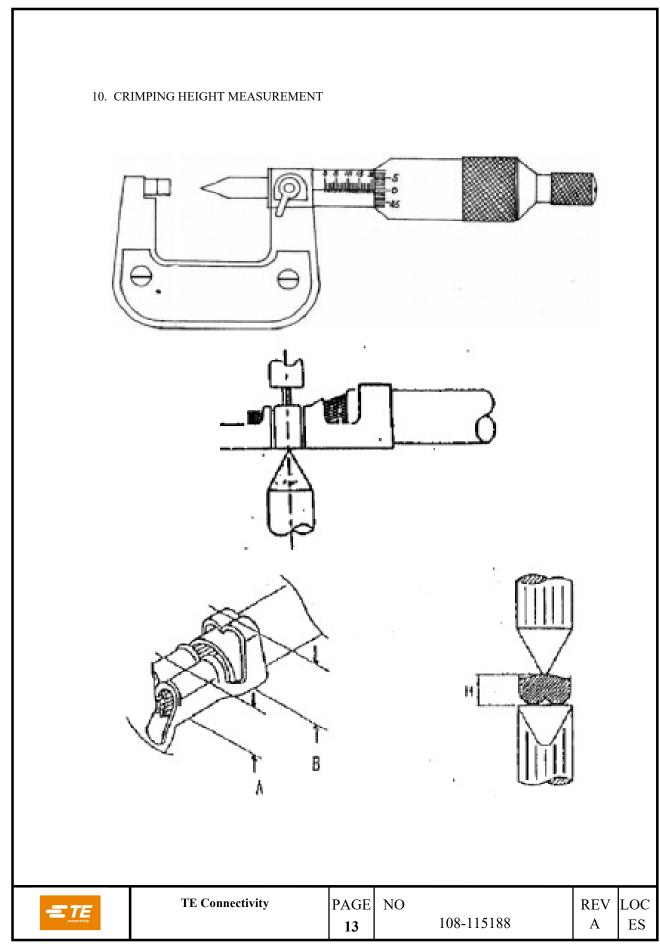
2 · W2: Insulation Crimping Width

3 · A: Conductor Crimping height

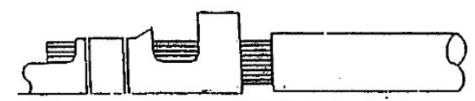
4 · B: Insulation Crimping height

5 · Strip length : 1.2~1.6mm

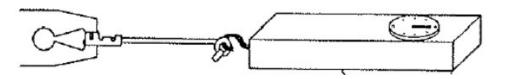
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| connectivity | | 12 | 108-115188 | A | ES |



11. PULL FORCE OF CRIMPING SECTION MEASUREMENT

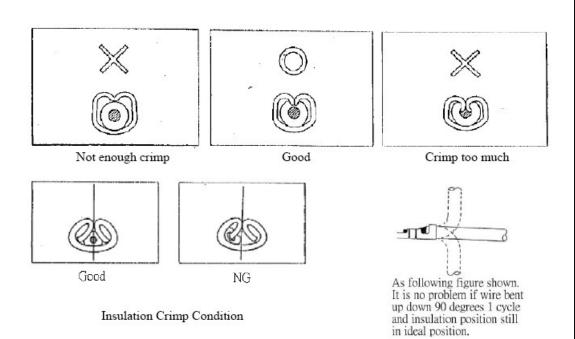


Before test samples, please measure crimp height and do not crimp insulation.

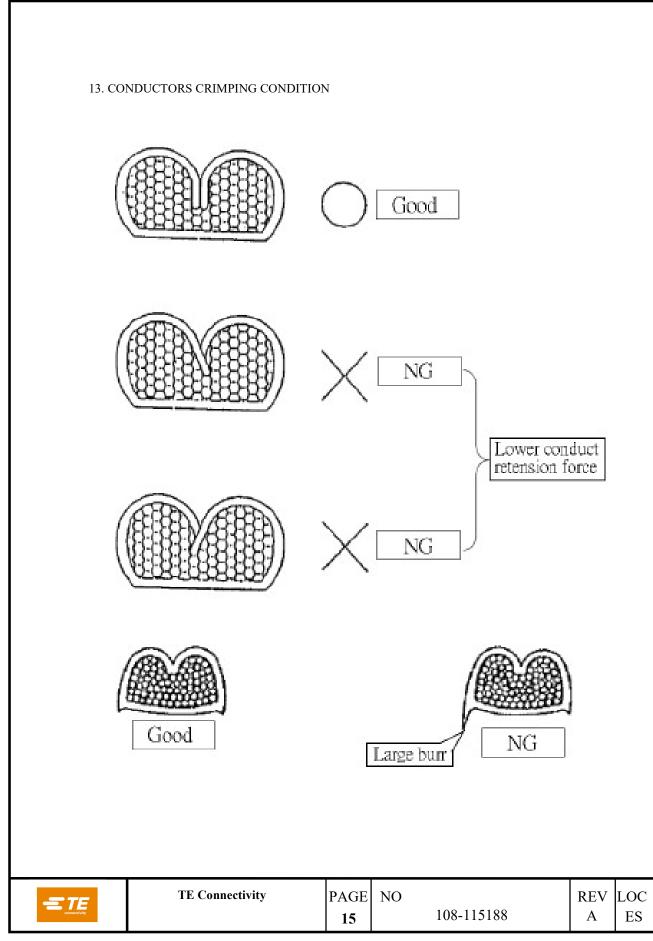


Pull Force of Crimp Section Measurement

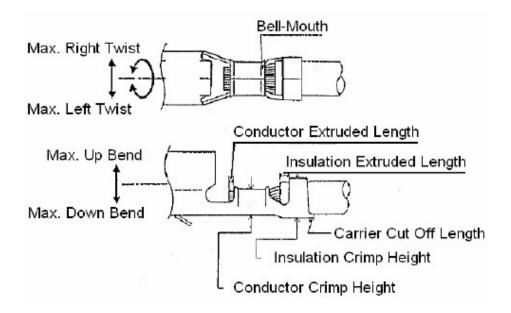
12. STANDARD INSULATION CRIMPING



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| connectivity | | 14 | 108-115188 | A | ES |



14 CRIMPING REQUIREMENTS



| Item | Range(Ref.) |
|---------------------------|-------------|
| Max. Up Bend | 6° |
| Max. Down Bend | 6° |
| Max. Left Twist | 5° |
| Max. Right Twist | 5° |
| Bell-Mouth Length | 0.1~0.3mm |
| Carrier Cut Off Length | 0~0.2mm |
| Conductor Extruded Length | 0.1~0.3mm |

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| connectivity | | 16 | 108-115188 | A | ES |